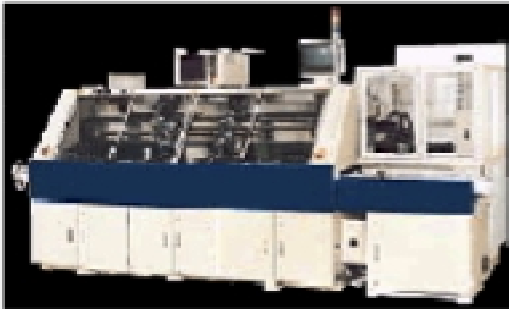


Multi Function SMD Mounter

IP-III (E)



Long selling super high accuracy placer.

The IP-III was developed with the goal of producing a machine of unparalleled accuracy. With the IP-III, BGAs, connectors and other components that caused problems for previous odd-form placers are breakthroughs which help you handle the trend toward increasing diversification in odd-form components.

■ Closed Loop Ensures High Placing Accuracy

A high-resolution linear scale is used, and a closed loop system controls the placing heads and Y-table.

In a world of semi-closed loop mounters, the IP-III is a step ahead.

■ Nozzle Variability

Up to 6 nozzles can be installed at each placing head giving a total of twelve. Users can select from over 10 nozzle types to suit their optimum set up. With the addition of an option, 24 nozzles can be installed, and if mechanical chucks are also prepared, the handling of components of virtually any shape and size is possible.

Specifications

■ Placing Head

■ Range of Nozzles

- Placeable component range from 1005s (in. 0402) to 74 x 74 mm.
- Nozzle Station

■ Odd Form Parts Compatibility

- Special Nozzles and Mechanical Chucks

■ Handling of BGAs with the addition of the second holding position on the component carrier (optional).

■ Components with fine pitch leads (0.15 mm) can be placed using the narrow view camera.

■ Placing rate 0.55 seconds /component for small chips, 1.25 sec. /component for ICs and 2.5 sec./component for tray components (under optimal conditions).

■ Placing accuracy of ± 0.025 mm for QFPs, GQFPs and TABs and ± 0.1 mm for non-quadpack components.

■ Large Board Capability

■ Closed Loop Ensures High Accuracy

■ Vision system

■ #12/13 camera

■ Feeder Units

- Multi-Feeder Unit (MFU-3/3L)
- Multi-Tray Unit (MTU-4)

Specifications

PCB dimensions

Max.: 508mm X 457mm Min.: 80mm X 50mm
t = 0.5 to 4.0mm (Option required for handling of PCBs of less than 0.8 mm in thickness)

Component capacity

Tape: Up to 74 types Stick: Up to 38 types
Tray: Up to 40 types

Placing Rate

Approx. 0.55 sec. / component for small chips
1.25 sec. / component for ICs
2.5 sec. / component for tray components

Applicable components

1005 (in. 0402) to 74 x 74 mm (with options)

Placing accuracy (fiducial mark reference)

Within ± 0.025 mm for 4-side leaded components
 ± 0.01 for other components

Power

3-phase, 200 to 480 VAC ICM: 2.0kVA

Air supply

0.5 MPa (5 kgf / cm²), 300NI / min.

Machine dimensions

L: 3185 mm (3990 mm with MTU-4) W: 2530 mm
H: 1850 mm (H: excluding signal tower)

Weight

Approx. 4000 kg (with MTU-4: Approx. 5100 kg)

Options

- Odd-form component handling (special nozzles, mechanical chucks)
- Coplanarity check
- Multi-Feeder Unit (MFU-3 / MFU-3L)
- Multi-Tray Unit (MTU-4)
- Programmable placing pressure
- Foreground lighting for component inspection
- HELPS (computerized job change assistance system)